

Project Number: Design Qualification Test Report	Tracking Code: 138890_Report_Rev_2		
Requested by: James Borgelt	Date: 8/22/2012	Product Rev: N/A	
Part #: ACP-16-06-H-00.35-T-S-P-1\ ACR-16-06-H-00.35-S-S1-P-1	Lot #: N/A	Tech: Craig Ryan	Eng: Eric Mings
Part description: ACP\ACR		Qty to test: 30	
Test Start: 05/02/2011	Test Completed: 05/23/2011		



DESIGN QUALIFICATION TEST REPORT

ACP\ACR
ACP-16-06-H-00.35-T-S-P-1\ ACR-16-06-H-00.35-S-S1-P-1

CERTIFICATION

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to ISO 10012-1 and ANSI/NCSL 2540-1, as applicable.

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SCOPE

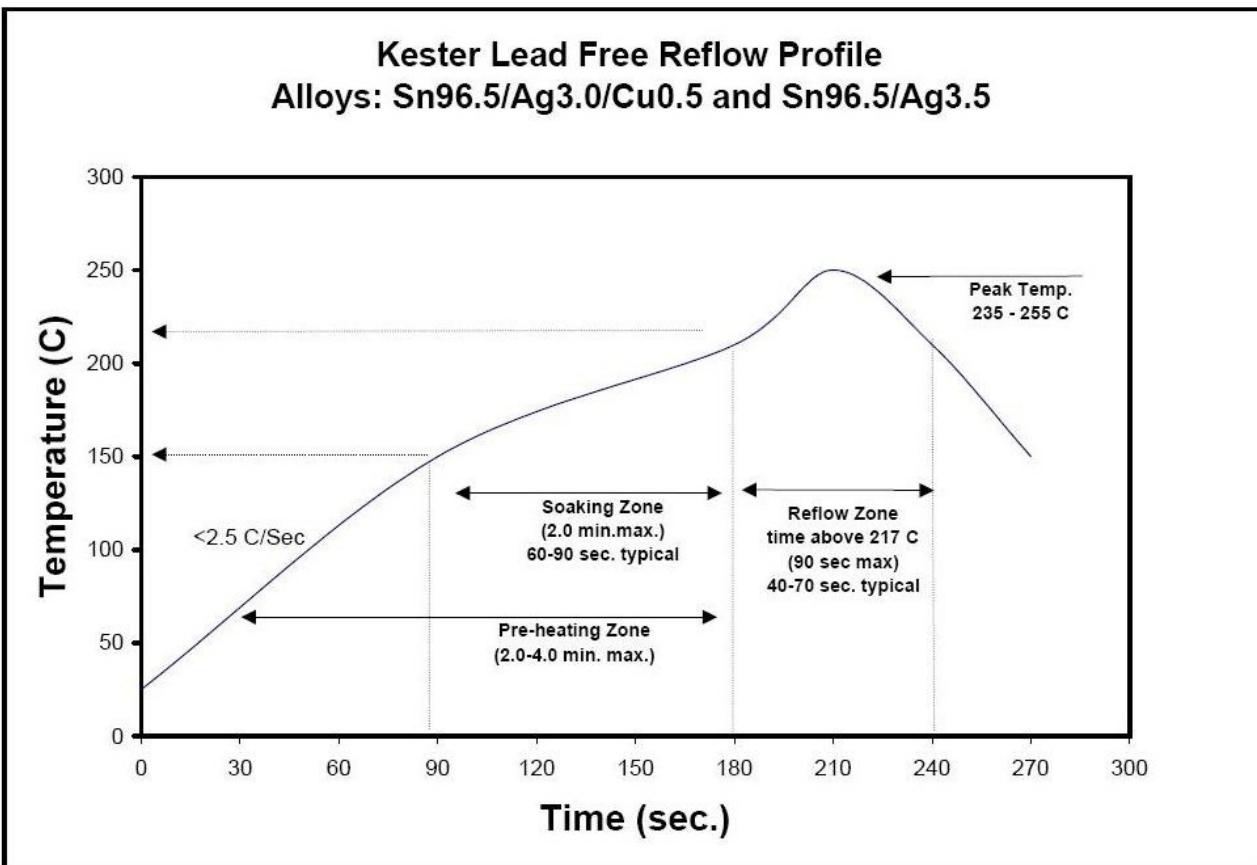
To perform the following tests: Design Qualification test. Please see test plan.

APPLICABLE DOCUMENTS

Standards: EIA Publication 364

TEST SAMPLES AND PREPARATION

- 1) All materials were manufactured in accordance with the applicable product specification.
- 2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
- 3) After soldering, the parts to be used for LLCR and DWV/IR testing were cleaned according to TLWI-0001.
- 4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
- 5) The automated procedure is used with aqueous compatible soldering materials.
- 6) Parts not intended for testing LLCR and DWV/IR are visually inspected and cleaned if necessary.
- 7) Any additional preparation will be noted in the individual test sequences.
- 8) Solder Information: Lead Free
- 9) Re-Flow Time/Temp: See accompanying profile.
- 10) Samtec Test PCBs used: PCB-103219-TST-XX

TYPICAL OVEN PROFILE (Soldering Parts to Test Boards)

FLOWCHARTS**IR & DWV**

TEST STEP	GROUP A1 2 Mated Sets Break Down Pin-to-Pin	GROUP A2 2 Unmated of Part # Being Tested Break Down Pin-to-Pin	GROUP A3 2 Unmated of Mating Part # Break Down Pin-to-Pin	GROUP B1 2 Mated Sets Pin-to-Pin
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

DWV on Group B1 to be performed at Test Voltage

DWV test voltage is equal to 75% of the lowest break down voltage from Groups A1, A2 or A3

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

IR = EIA-364-21

DWV = EIA-364-20, Test Condition 1

FLOWCHARTS Continued**Durability/Mating/Unmating/Gaps**

TEST STEP	GROUP A1 6 Assemblies
02	LLCR-1
03	Forces - Mating / Unmating
04	25 Cycles
05	Forces - Mating / Unmating
06	25 Cycles (50 Total)
07	Forces - Mating / Unmating
08	25 Cycles (75 Total)
09	Forces - Mating / Unmating
10	25 Cycles (100 Total)
11	Forces - Mating / Unmating
12	Clean w/Compressed Air
14	LLCR-2
15	Thermal Shock (Mated and Undisturbed)
16	LLCR-3
17	Cyclic Humidity (Mated and Undisturbed)
18	LLCR-4
19	Forces - Mating / Unmating

Thermal Shock = **EA-364-32, Table II, Test Condition I:**

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = **EA-364-31, Test Condition B (240 Hours)**

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

Mating / Unmating Forces = **EA-364-13**

LLCR = **EA-364-23, LLCR**

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

FLOWCHARTS Continued

Current Carrying Capacity - Array

TEST STEP	GROUP A1 3 Mated Assemblies All Contacts Powered
01	CCC

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C
after derating 20% and based on 105°C

(GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C
after derating 20% and based on 125°C

CCC, Temp rise = EIA-364-70

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

THERMAL SHOCK:

- 1) EIA-364-32, *Thermal Shock (Temperature Cycling) Test Procedure for Electrical Connectors.*
- 2) Test Condition 1: -55°C to +85°C
- 3) Test Time: ½ hour dwell at each temperature extreme
- 4) Number of Cycles: 100
- 5) All test samples are pre-conditioned at ambient.
- 6) All test samples are exposed to environmental stressing in the mated condition.

HUMIDITY:

- 1) Reference document: EIA-364-31, *Humidity Test Procedure for Electrical Connectors.*
- 2) Test Condition B, 240 Hours.
- 3) Method III, +25° C to + 65° C, 90% to 98% Relative Humidity excluding sub-cycles 7a and 7b.
- 4) All samples are pre-conditioned at ambient.
- 5) All test samples are exposed to environmental stressing in the mated condition.

MATING/UNMATING:

- 1) Reference document: EIA-364-13, *Mating and Unmating Forces Test Procedure for Electrical Connectors.*
- 2) The full insertion position was to within 0.003" to 0.004" of the plug bottoming out in the receptacle to prevent damage to the system under test.
- 3) One of the mating parts is secured to a floating X-Y table to prevent damage during cycling.

LLCR:

- 1) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
- 2) The following guidelines are used to categorize the changes in LLCR as a result from stressing
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms: ----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms: ----- Unstable
 - f. >+2000 mOhms: ----- Open Failure

ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

INSULATION RESISTANCE (IR):

To determine the resistance of insulation materials to leakage of current through or on the surface of these materials when a DC potential is applied.

- 1) PROCEDURE:
 - a. Reference document: EIA-364-21, *Insulation Resistance Test Procedure for Electrical Connectors*.
 - b. Test Conditions:
 - i. Between Adjacent Contacts or Signal-to-Ground
 - ii. Electrification Time 2.0 minutes
 - iii. Test Voltage (500 VDC) corresponds to calibration settings for measuring resistances.
- 2) MEASUREMENTS:
 - a. When the specified test voltage is applied (VDC), the insulation resistance shall not be less than 1000 MegOhms.

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

To determine if the sockets can operate at its rated voltage and withstand momentary over potentials due to switching, surges, and other similar phenomenon. Separate samples are used to evaluate the effect of environmental stresses so not to influence the readings from arcing that occurs during the measurement process.

- 1) PROCEDURE:
 - a. Reference document: EIA-364-20, *Withstanding Voltage Test Procedure for Electrical Connectors*.
 - b. Test Conditions:
 - i. Between Adjacent Contacts or Signal-to-Ground
 - ii. Barometric Test Condition 1
 - iii. Rate of Application 500 V/Sec
 - iv. Test Voltage (VAC) until breakdown occurs
- 2) MEASUREMENTS/CALCULATIONS
 - a. The breakdown voltage shall be measured and recorded.
 - b. The dielectric withstand voltage shall be recorded as 75% of the minimum breakdown voltage.
 - c. The working voltage shall be recorded as one-third (1/3) of the dielectric withstand voltage (one-fourth of the breakdown voltage).

ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

TEMPERATURE RISE (Current Carrying Capacity, CCC):

- 1) EIA-364-70, *Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets*.
- 2) When current passes through a contact, the temperature of the contact increases as a result of I^2R (resistive) heating.
- 3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
- 4) The size of the temperature probe can affect the measured temperature.
- 5) Copper traces on PC boards will contribute to temperature rise:
 - a. Self heating (resistive)
 - b. Reduction in heat sink capacity affecting the heated contacts
- 6) A de-rating curve, usually 20%, is calculated.
- 7) Calculated de-rated currents at three temperature points are reported:
 - a. Ambient
 - b. 80°C
 - c. 95°C
 - d. 115°C
- 8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
- 9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
- 10) A computer program, *TR 803.exe*, ensures accurate stability for data acquisition.
- 11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
- 12) Hook-up wire length is longer than the minimum specified in the referencing standard.

RESULTS

Temperature Rise, CCC at a 20% de-rating

- CCC for a 30°C Temperature Rise -----11.6 A per contact with all powered (Contact Interface)
(Powered the 28 AWG at 1/2 rated current (1 amp) and monitor the temp rise on the 16 AWG pins)

Mating – Unmating Forces

Mating\Unmating Durability Group

- Initial
 - Mating
 - Min -----3.44 Lbs
 - Max-----4.51 Lbs
 - Unmating
 - Min -----1.88 Lbs
 - Max-----2.60 Lbs
- After 25 Cycles
 - Mating
 - Min -----3.74 Lbs
 - Max-----5.44 Lbs
 - Unmating
 - Min -----2.77 Lbs
 - Max-----3.88 Lbs
- After 50 Cycles
 - Mating
 - Min -----4.01 Lbs
 - Max-----6.27 Lbs
 - Unmating
 - Min -----3.09 Lbs
 - Max-----4.42 Lbs
- After 75 Cycles
 - Mating
 - Min -----4.26 Lbs
 - Max-----6.81 Lbs
 - Unmating
 - Min -----3.28 Lbs
 - Max-----4.95 Lbs
- After 100 Cycles
 - Mating
 - Min -----4.42 Lbs
 - Max-----7.66 Lbs
 - Unmating
 - Min -----3.61 Lbs
 - Max-----5.47 Lbs
- After Humidity
 - Mating
 - Min -----3.46 Lbs
 - Max-----4.99 Lbs
 - Unmating
 - Min -----2.26 Lbs
 - Max-----2.68 Lbs

RESULTS Continued

Insulation Resistance minimums, IR

16 AWG to 28 AWG:

- **Initial**
 - Mated ----- 25000 Meg Ohms ----- Pass
 - Unmated----- 25000 Meg Ohms ----- Pass
- **Thermal**
 - Mated ----- 100000 Meg Ohms ----- Pass
 - Unmated----- 100000 Meg Ohms ----- Pass
- **Humidity**
 - Mated ----- 2100 Meg Ohms ----- Pass
 - Unmated----- 6000 Meg Ohms ----- Pass

28 AWG to 28 AWG:

- **Initial**
 - Mated ----- 25000 Meg Ohms ----- Pass
 - Unmated----- 25000 Meg Ohms ----- Pass
- **Thermal**
 - Mated ----- 100000 Meg Ohms ----- Pass
 - Unmated----- 100000 Meg Ohms ----- Pass
- **Humidity**
 - Mated ----- 3500 Meg Ohms ----- Pass
 - Unmated----- 5000 Meg Ohms ----- Pass

Dielectric Withstanding Voltage minimums, DWV

- **Minimums**
 - Breakdown Voltage ----- 1200 VAC
 - Test Voltage ----- 900 VAC
 - Working Voltage ----- 300 VAC

16 AWG to 28 AWG:

- Initial DWV ----- Passed
- Thermal DWV ----- Passed
- Humidity DWV ----- Passed

28 AWG to 28 AWG:

- Initial DWV ----- Passed
- Thermal DWV ----- Passed
- Humidity DWV ----- Passed

RESULTS Continued

LLCR:

Mating\Unmating Durability Group (80 LLCR test points)

16 AWG pin:

- Initial ----- 7.87 mOhms Max
- Durability, 100 Cycles
 - <= +5.0 mOhms----- 16 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure
- Thermal
 - <= +5.0 mOhms----- 16 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure
- Humidity
 - <= +5.0 mOhms----- 16 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure

28 AWG pin:

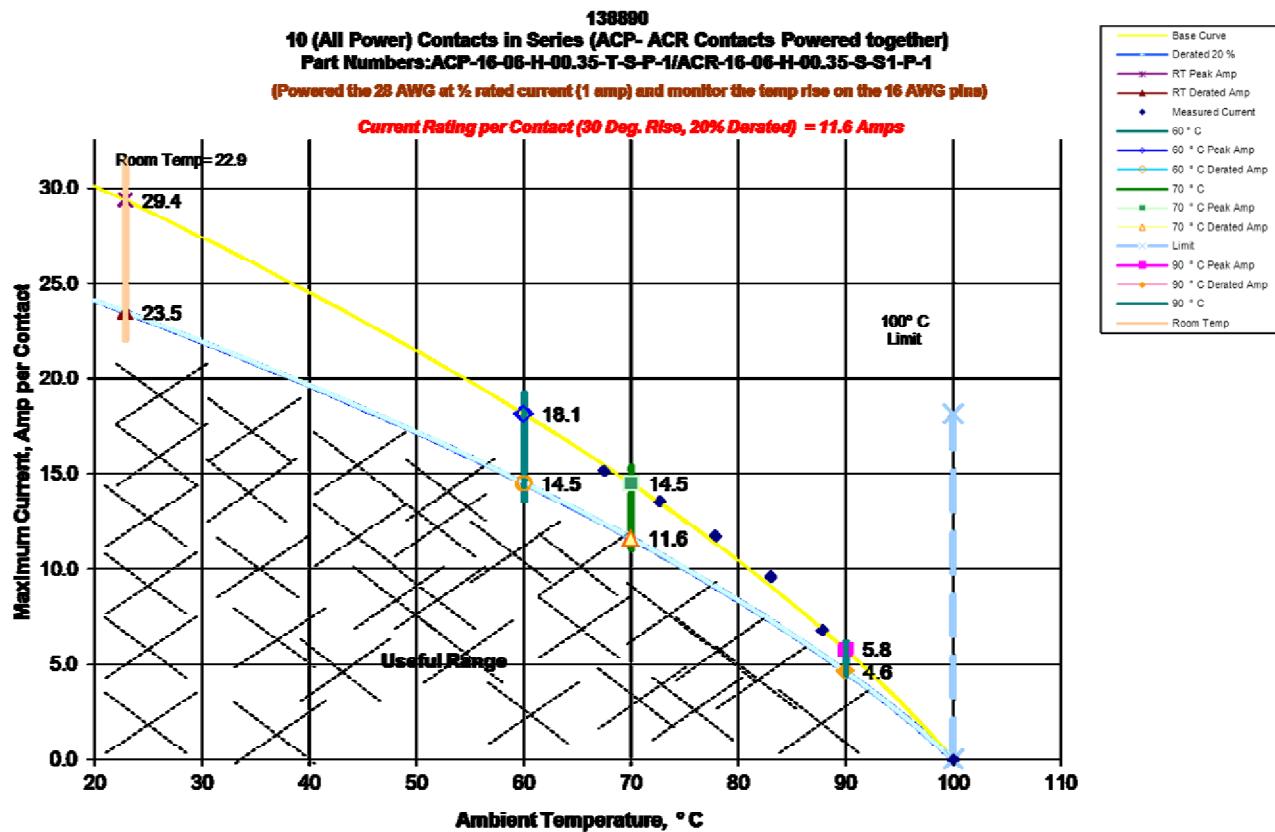
- Initial ----- 109.74 mOhms Max
- Durability, 100 Cycles
 - <= +5.0 mOhms----- 64 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure
- Thermal
 - <= +5.0 mOhms----- 64 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure
- Humidity
 - <= +5.0 mOhms----- 63 Points ----- Stable
 - +5.1 to +10.0 mOhms ----- 0 Points ----- Minor
 - +10.1 to +15.0 mOhms ----- 1 Points ----- Acceptable
 - +15.1 to +50.0 mOhms ----- 0 Points ----- Marginal
 - +50.1 to +2000 mOhms ----- 0 Points ----- Unstable
 - >+2000 mOhms ----- 0 Points ----- Open Failure

DATA SUMMARIES

TEMPERATURE RISE (Current Carrying Capacity, CCC):

- 1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.
- 2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.
- 3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less than 1°C (computer controlled data acquisition).
- 4) Adjacent contacts were powered:

- a. Linear configuration with all All Power (All contact powered)



DATA SUMMARIES Continued

MATING/UNMATING FORCE:

Mating\Unmating Durability Group

	Initial				25 Cycles			
	Mating		Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	15.30	3.44	8.36	1.88	16.64	3.74	12.32	2.77
Maximum	20.06	4.51	11.56	2.60	24.20	5.44	17.26	3.88
Average	18.20	4.09	10.14	2.28	21.53	4.84	14.23	3.20
St Dev	2.03	0.46	0.98	0.22	2.92	0.66	1.86	0.42
Count	8	8	8	8	8	8	8	8
	50 Cycles				75 Cycles			
	Mating		Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	17.84	4.01	13.74	3.09	18.95	4.26	14.59	3.28
Maximum	27.89	6.27	19.66	4.42	30.29	6.81	22.02	4.95
Average	24.12	5.42	16.58	3.73	26.02	5.85	18.38	4.13
St Dev	3.70	0.83	2.02	0.45	4.19	0.94	2.81	0.63
Count	8	8	8	8	8	8	8	8
	100 Cycles				After Humidity			
	Mating		Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	19.66	4.42	16.06	3.61	15.39	3.46	10.05	2.26
Maximum	34.07	7.66	24.33	5.47	22.20	4.99	11.92	2.68
Average	27.90	6.27	20.29	4.56	18.81	4.23	11.34	2.55
St Dev	4.82	1.08	3.10	0.70	2.24	0.50	0.62	0.14
Count	8	8	8	8	8	8	8	8

DATA SUMMARIES Continued**INSULATION RESISTANCE (IR):**

		Power to Signal		
		Mated	Unmated	Unmated
Minimum	ACP/ACR	ACP	ACP	ACR
Initial	25000	50000	25000	
Thermal	100000	100000	100000	
Humidity	2100	5000	6000	

		Signal to Signal		
		Mated	Unmated	Unmated
Minimum	ACP/ACR	ACP	ACP	ACR
Initial	25000	50000	25000	
Thermal	100000	100000	100000	
Humidity	3500	8000	5000	

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

Voltage Rating Summary	
Minimum	ACP/ACR
Break Down Voltage	1200
Test Voltage	900
Working Voltage	300

Pin to Pin	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Row to Row	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

DATA SUMMARIES Continued

LLCR:

Mating\Unmating Durability Group

- 1) A total of 80 points were measured.
- 2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
- 3) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. $\leq +5.0$ mOhms: ----- Stable
 - b. $+5.1$ to $+10.0$ mOhms: ----- Minor
 - c. $+10.1$ to $+15.0$ mOhms: ----- Acceptable
 - d. $+15.1$ to $+50.0$ mOhms: ----- Marginal
 - e. $+50.1$ to $+2000$ mOhms ----- Unstable
 - f. $>+2000$ mOhms: ----- Open Failure

LLCR Measurement Summaries by Pin Type				
	Date	12/2/2011	12/14/2011	12/20/2011
	1/3/2012	22	23	23
Room Temp (Deg C)	29	35	33	32
	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim
Technician	Actual	Delta	Delta	Delta
	Initial	100 Cycles	Therm Shck	Humidity
Pin Type 1: 28 AWG				
Average	100.42	0.30	0.47	1.03
	3.62	0.70	0.58	1.61
St. Dev.	93.63	0.00	0.02	0.02
	109.74	3.59	2.55	10.02
Min	64	64	64	64
	64	64	64	64
Pin Type 2: 16 AWG				
Average	7.44	0.03	0.10	0.04
	0.21	0.03	0.08	0.02
St. Dev.	7.20	0.00	0.05	0.01
	7.87	0.11	0.32	0.12
Min	16	16	16	16
	16	16	16	16
Max	16	16	16	16
	16	16	16	16

LLCR Delta Count by Category						
mOhms	Stable	Minor	Acceptable	Marginal	Unstable	Open
	≤ 5	$>5 \text{ & } \leq 10$	$>10 \text{ & } \leq 15$	$>15 \text{ & } \leq 50$	$>50 \text{ & } \leq 1000$	>1000
100 Cycles	80	0	0	0	0	0
Therm Shck	80	0	0	0	0	0
Humidity	79	0	1	0	0	0

EQUIPMENT AND CALIBRATION SCHEDULES

Equipment #: MO-04**Description:** Multimeter /Data Acquisition System**Manufacturer:** Keithley**Model:** 2700**Serial #:** 0798688**Accuracy:** See Manual

... Last Cal: 04/30/2011, Next Cal: 04/30/2012

Equipment #: PS-07**Description:** Power Supply**Manufacturer:** Agilent**Model:** AT-6031A**Serial #:** 2721A00648**Accuracy:** See Manual See Manual

... Last Cal: 08/21/2010, Next Cal: 08/21/2011

Equipment #: TCT-04**Description:** Dillon Quantrol TC2 Test Stand**Manufacturer:** Dillon Quantrol**Model:** TC2**Serial #:** 04-1041-04**Accuracy:** Speed Accuracy: +/- 5% of indicated speed; Displacement: +/- 5 micrometers.

... Last Cal: 05/21/2011, Next Cal: 05/21/2012

Equipment #: THC-02**Description:** Temperature/Humidity Chamber**Manufacturer:** Thermotron**Model:** SE-1000-6-6**Serial #:** 31808**Accuracy:** See Manual

... Last Cal: 02/16/2011, Next Cal: 02/16/2012

Equipment #: HPM-01**Description:** Hipot Megommeter**Manufacturer:** Hipotronics**Model:** H306B-A**Serial #:** M9905004**Accuracy:** 2 % Full Scale Accuracy

... Last Cal: 11/30/2010, Next Cal: 11/30/2011